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Part Number: 0739436000
Status: Active
Overview: HDM Backplane Connector System
Description: HDM Board-to-Board Backplane Header, Vertical, Solder Tail, Closed End, 72 Circuits

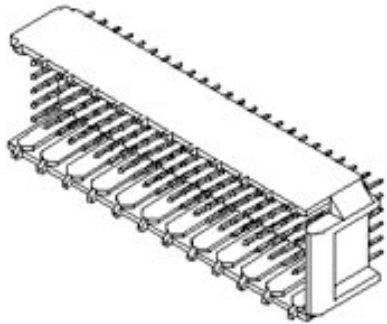
Documents:
[3D Model](#) [Packaging Specification PK-70873-0818 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)
[3D Model \(PDF\)](#)

Agency Certification
CSA LR19980
UL E29179

General
Product Family Backplane Connectors
Series 73943
Application Backplane
Comments Solder Tail, Solder Tail
Component Type PCB Header
Overview HDM Backplane Connector System
Product Name HDM
UPC 800754887380

Physical
Circuits (Loaded) 72
Circuits (maximum) 72
Color - Resin Black, Natural
Durability (mating cycles max) 250
First Mate / Last Break No
Flammability 94V-0
Guide to Mating Part No
Keying to Mating Part None
Material - Metal Phosphor Bronze
Material - Plating Mating Gold
Material - Plating Termination Tin
Material - Resin High Temperature Thermoplastic
Net Weight 3.554/g
Number of Columns 12
Number of Pairs Open Pin Field
Number of Rows 6
Orientation Vertical
PC Tail Length 3.50mm
PCB Locator No
PCB Retention None
PCB Thickness - Recommended 2.50mm
Packaging Type Tube
Pitch - Mating Interface 2.00mm
Pitch - Termination Interface 2.00mm
Plating min - Mating 0.762µm
Plating min - Termination 2.540µm
Stackable Yes
Surface Mount Compatible (SMC) Yes
Temperature Range - Operating -55° to +105°C
Termination Interface: Style Through Hole

Electrical



Series image - Reference only

EU ELV
Not Relevant

EU RoHS **China RoHS**
Compliant
REACH SVHC
Not Contained Per -
ED/71/2019 (16 July
2019)
Halogen-Free
Status
Low-Halogen
For more information, please visit [Contact US](#)

China ROHS Green Image
ELV Not Relevant
RoHS Phthalates Not Contained

Search Parts in this Series
73943 Series

Mates With
73632 HDM+ Board-to-Board Daughtercard
Receptacle. 73780 HDM Board-to-Board
Daughtercard Receptacle

Application Tooling | FAQ
*Tooling specifications and manuals are
found by selecting the products below.
Crimp Height Specifications are then
contained in the Application Tooling
Specification document.*

Global	
Description	Product #
Extraction Tool	621001000
Backplane Insertion	621001400
Signal Contact Tool	
Backplane Signal	622008502
Insertion Module	
Press-In Tool for	
2.00mm Pitch HDM*	
Board-to-Board	
Backplane Header	

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Voltage - Maximum	250V AC
Solder Process Data	
Duration at Max. Process Temperature (seconds)	040
Lead-freeProcess Capability	SMC&WAVE
Max. Cycles at Max. Process Temperature	003
Process Temperature max. C	260
Material Info	
Reference - Drawing Numbers	
Packaging Specification	PK-70873-0818
Sales Drawing	SD-73943-001

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